

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Chen-Fu Chu</td> <td>06/26/2013</td> </tr> <tr> <td>Hao-Chun Cheng</td> <td>06/29/2013</td> </tr> <tr> <td>Trung Tri Doan</td> <td>07/05/2013</td> </tr> <tr> <td>Feng-Hsu Fan</td> <td>06/27/2013</td> </tr> </tbody> </table>		Name	Execution Date	Chen-Fu Chu	06/26/2013	Hao-Chun Cheng	06/29/2013	Trung Tri Doan	07/05/2013	Feng-Hsu Fan	06/27/2013
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<table border="1"> <tr> <td>Name:</td> <td>SemiLEDs Optoelectronics Co., Ltd.</td> </tr> <tr> <td>Street Address:</td> <td>3F, No. 11, Ke Jung Road, Chu Nan Site,</td> </tr> <tr> <td>Internal Address:</td> <td>Hsinchu Science Park</td> </tr> <tr> <td>City:</td> <td>Chu-nan 350, Miao-Li County</td> </tr> <tr> <td>State/Country:</td> <td>TAIWAN</td> </tr> </table>		Name:	SemiLEDs Optoelectronics Co., Ltd.	Street Address:	3F, No. 11, Ke Jung Road, Chu Nan Site,	Internal Address:	Hsinchu Science Park	City:	Chu-nan 350, Miao-Li County	State/Country:	TAIWAN
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PROPERTY NUMBERS Total: 1											
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CORRESPONDENCE DATA											
<p>Fax Number: 3039896538 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 303 989 6353 Email: steve@grattonlaw.com Correspondent Name: Stephen A. Gratton Address Line 1: 2764 S Braun Way Address Line 4: Lakewood, COLORADO 80228</p>											
ATTORNEY DOCKET NUMBER:	SP032USP1										
NAME OF SUBMITTER:	Stephen A. Gratton										
Signature:	/Stephen A. Gratton/										

Date:

07/12/2013

Total Attachments: 2

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

CHEN-FU CHU
HAO-CHUN CHENG
TRUNG TRI DOAN
FENG-HSU FAN

Serial No.: 13/936,337

Filing Date: 07-08-2013

Title: **METHOD FOR FABRICATING SEMICONDUCTOR DICE BY
SEPARATING A SUBSTRATE FROM SEMICONDUCTOR
STRUCTURES USING MULTIPLE LASER PULSES**

Docket No. SP032USP1

ASSIGNMENT:

 x Enclosed for recording
 Previously recorded

Date: _____
Reel: _____

A S S I G N M E N T

FOR GOOD AND VALUABLE CONSIDERATION, the receipt, sufficiency, and adequacy of which are hereby acknowledged, the undersigned do hereby:

SELL, ASSIGN, AND TRANSFER to SemiLEDs Optoelectronics Co., Ltd., a Taiwanese company with its business address at 3F, No. 11, Ke Jung Rd., Chu-Nan Site, Hsinchu Science Park, Chu-nan 350, Miao-Li County, Taiwan, R.O.C. (the "Assignee), the entire right, title, and interest for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent, which will be executed by the undersigned and is entitled: **METHOD FOR FABRICATING SEMICONDUCTOR DICE BY SEPARATING A SUBSTRATE FROM SEMICONDUCTOR STRUCTURES USING MULTIPLE LASER PULSES**; such application and all divisional, continuing, substitute, renewal, reissue, and all other applications for patent which have been or shall be filed in the United States and all foreign countries on any of such improvements; all original and reissued patents which have been or shall be issued in the United States and all foreign countries on such improvements; and specifically including the right to file foreign applications under the

provisions of any convention or treaty and claim priority based on such application in the United States of America;

AUTHORIZE AND REQUEST, the issuing authority to issue any and all United States and foreign patents granted on such improvements to the Assignee;

WARRANT AND COVENANT that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been or will be made to others by the undersigned, and that the full right to convey the same as herein expressed is possessed by the undersigned;

COVENANT that, when requested and at the expense of the Assignee, to carry out in good faith the intent and purpose of this assignment the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all such improvements; execute all rightful oaths, declarations, assignments, powers of attorney, and other papers; communicate to the Assignee all facts known to the undersigned relating to such improvements and the history thereof; and generally do everything possible which the Assignee shall consider desirable for securing, maintaining, and enforcing proper patent protection for such improvements and for vesting title to such improvements in the Assignee;

TO BE BINDING on the heirs, assigns, representatives, and successors of the undersigned and extend to the successors, assigns, and nominees of the Assignee.

Signature Chen-Fu Chu Date 2013.6.26.
CHEN-FU CHU

Signature Hao-chun Cheng Date 2013.6.29
HAO-CHEN CHENG

Signature Trung Tri Doan Date 2013.7.5
TRUNG TRI DOAN

Signature Feng-Hsu Fan Date 2013.6.27
FENG-HSU FAN